

# MBRP20060CT

## POWERTAP II Switch-mode Power Rectifier

These state-of-the-art devices use the Schottky Barrier principle with a platinum barrier metal.

### Features

- Dual Diode Construction – May Be Paralleled for Higher Current Output
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Pb-Free Package is Available\*

### Mechanical Characteristics:

- Case: Epoxy, Molded with metal heatsink base
- Weight: 80 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant
- Top Terminal Torque: 25–40 lb-in max
- Base Plate Torques: See procedure given in the Package Outline Section

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	60	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
Average Rectified Forward Current (Rated $V_R$ , $T_C = 140^\circ\text{C}$ )	$I_{F(AV)}$	100 200	A
	Per Leg Per Device		
Peak Repetitive Forward Current, (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 140^\circ\text{C}$ )	$I_{FRM}$	200	A
	Per Leg		
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	1500	A
Peak Repetitive Reverse Current (2.0 $\mu\text{s}$ , 1.0 kHz)	$I_{RRM}$	2.0	A
	Per Leg		
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ )	$dv/dt$	10,000	V/ $\mu\text{s}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

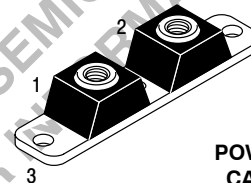
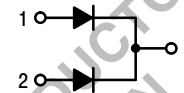
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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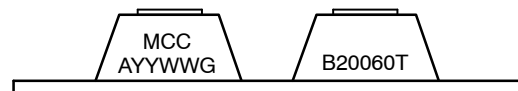
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## SCHOTTKY BARRIER RECTIFIER 200 AMPERES, 60 VOLTS



POWERTAP II  
CASE 357C  
PLASTIC

### MARKING DIAGRAM



B20060T = Specific Device Code  
MCC = Mold Compound Code  
A = Assembly Location  
YY = Year  
WW = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping
MBRP20060CT	POWERTAP II	25 Units/Tray
MBRP20060CTG	POWERTAP II (Pb-Free)	25 Units/Tray

# MBRP20060CT

## THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.6	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS (Per Leg)

Instantaneous Forward Voltage (Note 1) ( $i_F = 200$ Amps, $T_J = 25^{\circ}\text{C}$ ) ( $i_F = 200$ Amps, $T_J = 100^{\circ}\text{C}$ )	$V_F$	0.91 0.80	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 125^{\circ}\text{C}$ ) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$ )	$i_R$	50 0.5	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

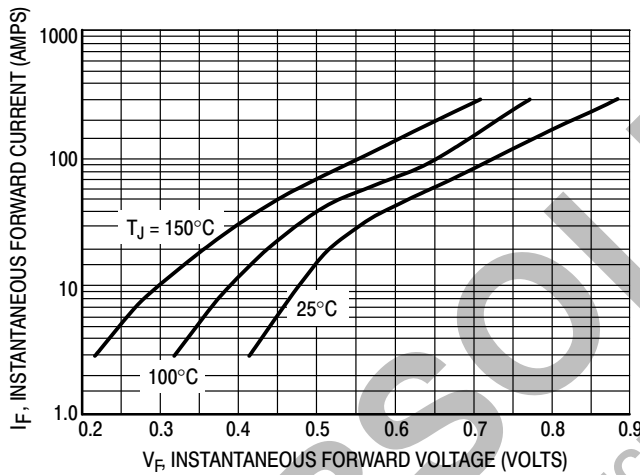


Figure 1. Typical Forward Voltage

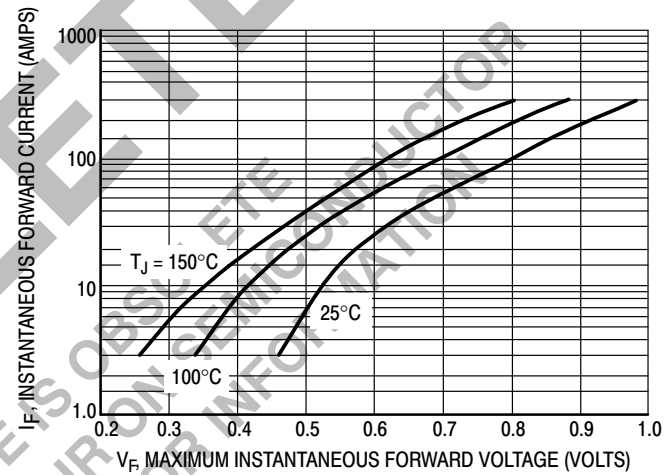


Figure 2. Maximum Forward Voltage

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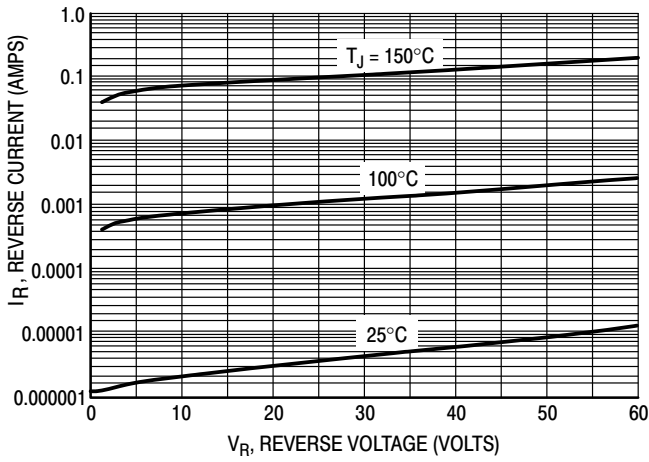


Figure 3. Typical Reverse Current

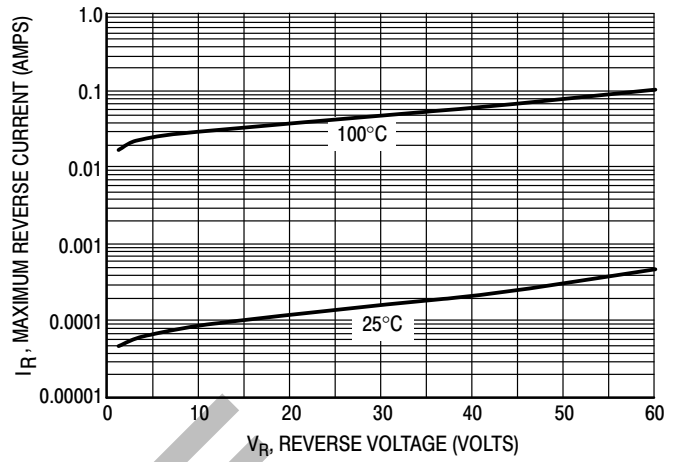


Figure 4. Maximum Reverse Current

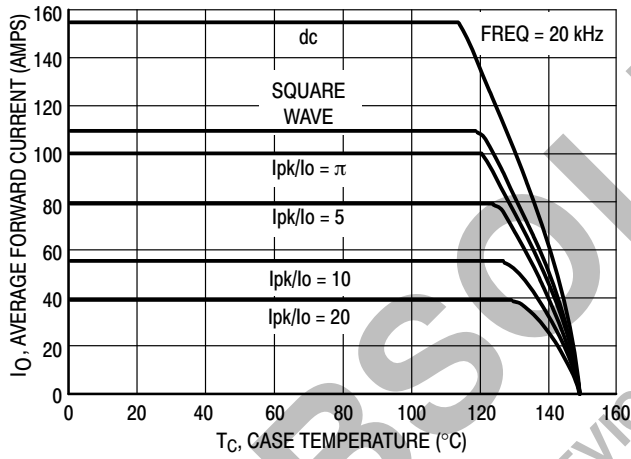


Figure 5. Current Derating (PER LEG)

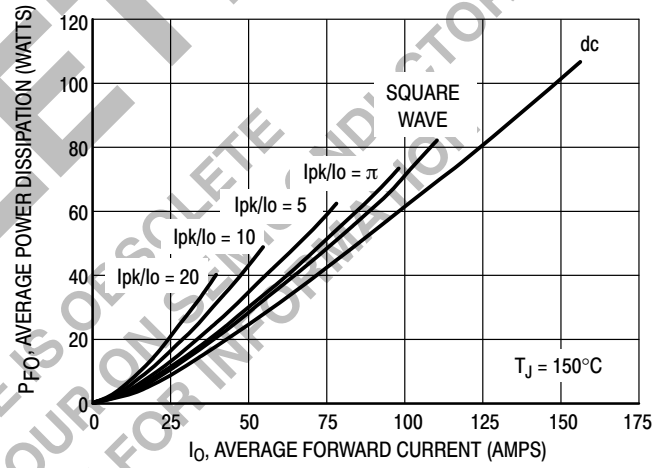


Figure 6. Forward Power Dissipation (PER LEG)

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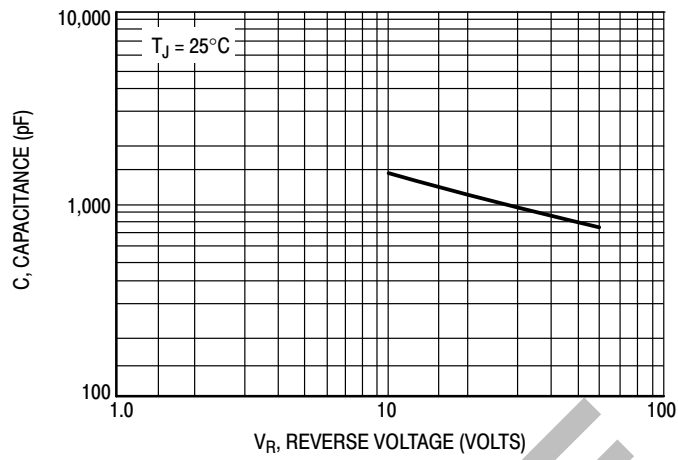


Figure 7. Capacitance

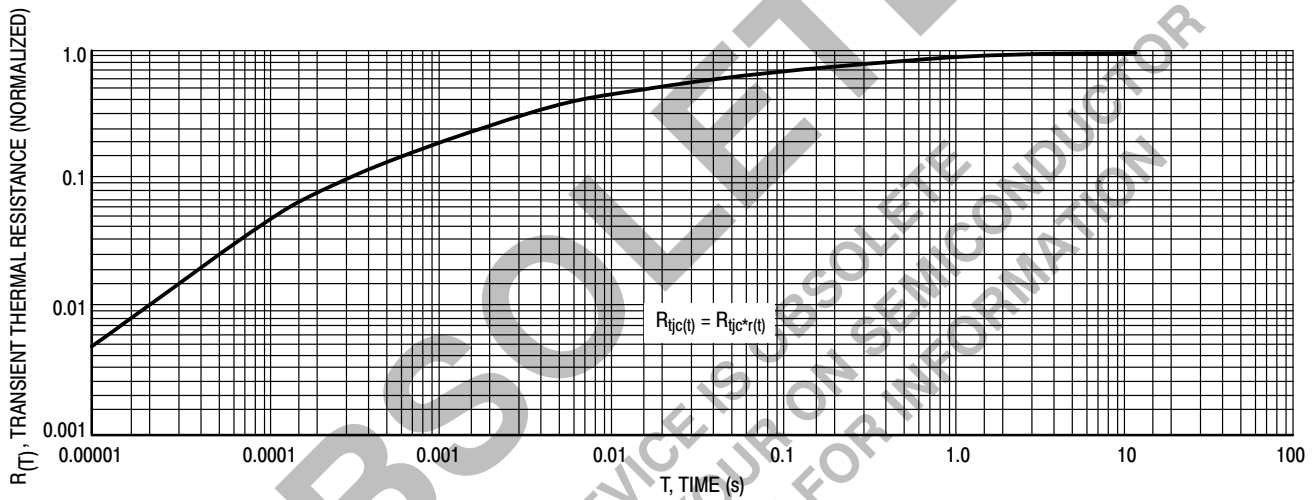


Figure 8. Thermal Response

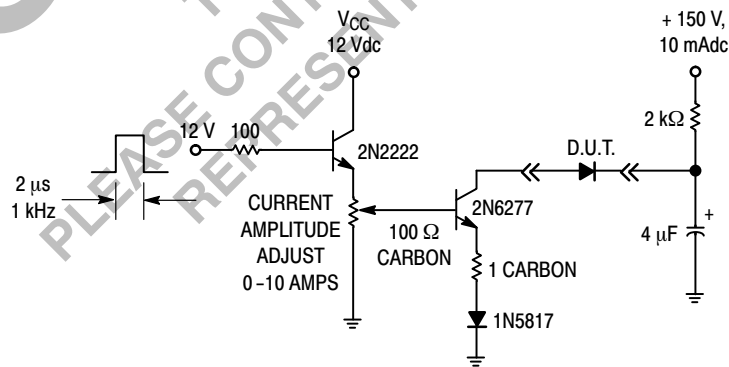


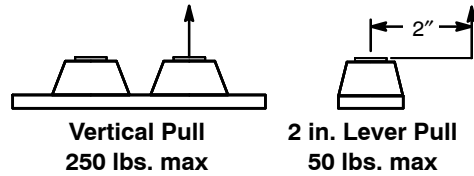
Figure 9. Test Circuit for Repetitive Reverse Current

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## MAXIMUM MECHANICAL RATINGS

Terminal Penetration:	0.235 max
Terminal Torque:	25-40 in-lb max
Mounting Torque — Outside Holes:	30-40 in-lb max
Mounting Torque — Center Hole:	8-10 in-lb max
Seating Plane Flatness	1 mil per in. (between mounting holes)

## POWERTAP MECHANICAL DATA APPLIES OVER OPERATING TEMPERATURE



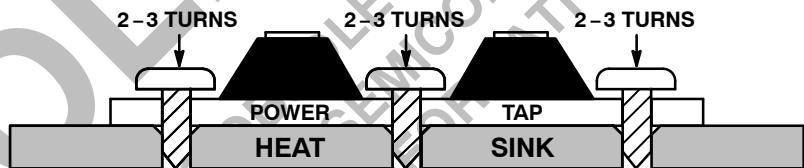
Note: While the POWERTAP is capable of sustaining these vertical and levered tensions, the intimate contact between POWERTAP and heat sink may be lost. This could lead to thermal runaway. The use of very flexible leads is recommended for the anode connections. Use of thermal grease is highly recommended.

## MOUNTING PROCEDURE

The POWERTAP package requires special mounting considerations because of the long longitudinal axis of the copper heat sink. It is important to follow the proper tightening sequence to avoid warping the heat sink, which can reduce thermal contact between the POWERTAP and heat sink.

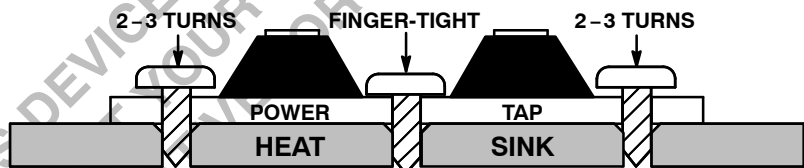
### STEP 1:

Locate the POWERTAP on the heat sink and start mounting bolts into the threads by hand (2 or 3 turns).



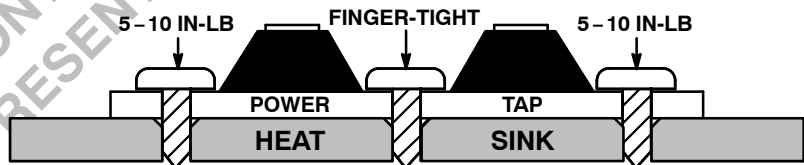
### STEP 2:

Finger tighten the center bolt. The bolt may catch on the threads of the heat sink so it is important to make sure the face of the bolt or washer is in contact with the surface of the POWERTAP.



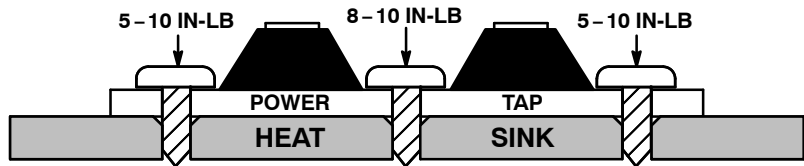
### STEP 3:

Tighten each of the end bolts between 5 to 10 in-lb.



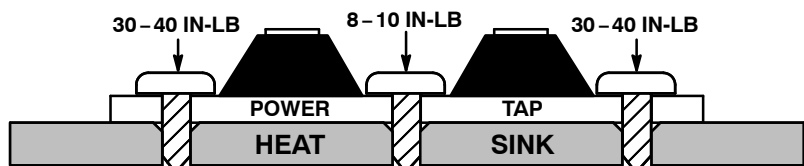
### STEP 4:

Tighten the center bolt between 8 to 10 in-lb.



### STEP 5:

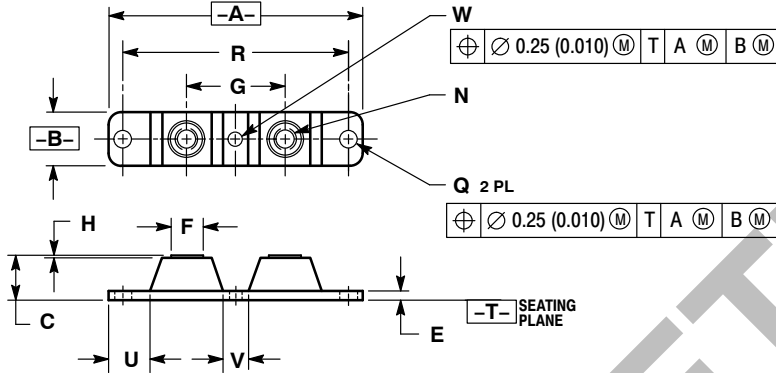
Finally, tighten the end bolts between 30 to 40 in-lb.



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## PACKAGE DIMENSIONS

CASE 357C-03  
 POWERTAP  
 PLASTIC PACKAGE  
 ISSUE E



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TERMINAL PENETRATION: 5.97 (0.235) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	3.450	3.635	87.63	92.33
B	0.700	0.810	17.78	20.57
C	0.615	0.640	15.63	16.26
E	0.120	0.130	3.05	3.30
F	0.435	0.445	11.05	11.30
G	1.370	1.380	34.80	35.05
H	0.007	0.030	0.18	0.76
N	1/4-20UNC-2B	1/4-20UNC-2B		
Q	0.270	0.285	6.86	7.23
R	31.50 BSC	80.01 BSC		
U	0.600	0.630	15.24	16.00
V	0.330	0.375	8.39	9.52
W	0.170	0.190	4.32	4.82

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